



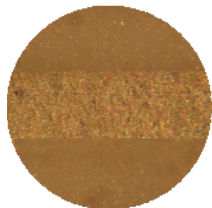
Direct Printing Fine Features – The ElectroSpense Advantage

Numerous applications in electronics assembly are requiring greater precision and miniaturization from the direct printing of thick film inks and pastes. Direct printing of thick films via conventional print processes enables advanced design concepts in solar cells, displays, RFID, and a host of emerging uses. Additionally, attainment of finer features via thick film printing allows the process designer to eliminate expensive thin film subtractive processes, driving significant cost savings.

ElectroSpense thick film conductor pastes are rheologically stable, easy-to-process materials, ideally suited for direct printing of fine features. Combining Five Star's patented hydrodynamic cavitation process with advanced particle technology, ElectroSpense inks and pastes are expanding the functionality of thick film technology. Screen printable grades can be printed to features as small as 50 μm . Grades designed for extrusion and digital print processes are achieving even smaller print features, enabling replacement of thin film processing. Five Star is truly creating . . . the future of functional inks.

Enable Advanced Direct Print Designs

- Direct print fine features consistently
- Eliminate expensive subtractive processes

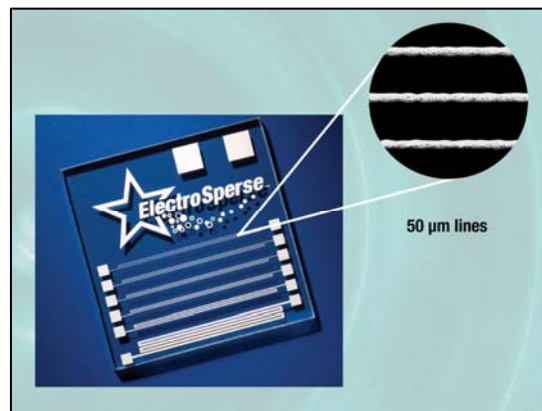


ElectroSpense Paste



Competitor

- More uniform print quality is achieved using ElectroSpense pastes



- Features as small as 50 μm can be screen printed with ElectroSpense inks

